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TECHNICAL REPORT

**Semiconductor die products –
Part 4: Questionnaire for die users and suppliers**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

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CONTENTS

FOREWORD.....	3
INTRODUCTION.....	5
1 Scope.....	6
2 Normative references.....	6
3 Terms and definitions	6
4 General	6
5 Data exchange	7
Annex A Customer questionnaire on die devices.....	8
Table A.1 – Basic data	9
Table A.2 – Bare die and wafers.....	10
Table A.3 – Die and wafers with connection structures	11
Table A.4 – Minimally-packaged die devices.....	12
Table A.5 – Quality, reliability and storage	12
Table A.6 – Terminal data	14
Table A.7 – Terminal geometries.....	15
Table A.8 – Polygon vertices	15
Table A.9 – Fiducial definitions.....	16
Table A.10 – Fiducial positions.....	17
Table A.11 – Simulator data	17
Table A.12 – Group defintions	18
Table A.13 – Permutations	19

INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DIE PRODUCTS –

Part 4: Questionnaire for die users and suppliers

FOREWORD

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The main task of IEC technical committees is to prepare International Standards. However, a technical committee may propose the publication of a technical report when it has collected data of a different kind from that which is normally published as an International Standard, for example "state of the art".

IEC 62258-4, which is a technical report, has been prepared by IEC technical committee 47: Semiconductor devices.

The text of this technical report is based on the following documents:

Enquiry draft	Report on voting
47/1884/DTR	47/1909/RVC

Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The list of all the parts of IEC 62258, under the general title *Semiconductor die products*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

INTRODUCTION

This technical report is based on the work carried out in the ESPRIT 4th Framework Project GOODDIE which resulted in the publication of the ES 59008 series of European specifications. Organizations that helped prepare this document included the ESPRIT ENCAST and ENCASIT projects, the Die Products Consortium, JEITA, JEDEC and ZVEI.

SEMICONDUCTOR DIE PRODUCTS –

Part 4: Questionnaire for die users and suppliers

1 Scope

This part of IEC 62258 has been developed to facilitate the production, supply and use of semiconductor die products, including

- wafers;
- singulated bare die;
- die and wafers with attached connection structures;
- minimally or partially encapsulated die and wafers.

This technical report contains a questionnaire, based on the requirements of other parts of IEC 62258, which may be used in negotiations and contracts between suppliers and purchasers of die devices. It is intended to assist all those involved in the supply chain for die devices to comply with the requirements of the IEC 62258-1 and IEC 62258-2 standards.

It should be recognized that the tables contained in this technical report form a checklist of information that can potentially be supplied and that it may not be relevant or possible to complete all fields. Different markets may require different subsets of the information requested herein.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050, *International Electrotechnical Vocabulary*

IEC 62258-1:2005, *Semiconductor die products – Part 1: Requirements for procurement and use*

IEC 62258-2:2005, *Semiconductor die products – Part 2: Exchange data formats*